

	Hits	Search Text	DBs
19	13	((substrate or wafer or workpiece or platen) same (barrier or protective or layer or coat\$4 or film or ARC or antireflect\$4 or BARC) same (resist or photoresist or photosensitive or photocur\$3 or (radiation near9 sensitive)) same crack\$2) and ((crack\$3 near24 (prevent\$4 or avoid or reduc\$4)) same (photoresist or resist or photosensitive) same (leak\$4 or transfer\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
20	27	((substrate or wafer or workpiece or platen) near16 (barrier or protective ARC or antireflect\$4 or BARC or poly\$3phenol\$4)) same (resist or photoresist or photosensitive or photocur\$3 or (radiation near9 sensitive)) same (crack\$3 near24 (prevent\$4 or avoid or reduc\$4)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
21	26	S26 NOT S25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
22	10	((substrate or wafer or workpiece or platen) near16 (barrier or protective ARC or antireflect\$4 or BARC or poly\$3phenol\$4)) same (resist or photoresist or photosensitive or photocur\$3 or (radiation near9 sensitive))) and ((crack\$3 near24 (resist or photoresist)) same ((barrier or protective or antireflect\$4) near16 (prevent or avoid or reduc\$4)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB